

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

<b>PCN Title:</b>	Expanding bumping/assembly processing to UTAC/Singapore/Thailand for MAX20404/MAX20405/MAX20406 (AE02/FC2QFN/F173A3FY+6/F153A3FY+2/F173A3F+2F)
<b>Publication Date:</b>	11-Sep-2023
<b>Effectivity Date:</b>	14-Dec-2023 <i>(the earliest date that a customer could expect to receive changed material)</i>
<b>Revision Description:</b>	

**Description Of Change:**

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 MAX20404/MAX20405/MAX20406  
 Current bump/final assembly processing at Advanced Semiconductor Engineering/Kaohsiung/Taiwan

**Reason For Change:**

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 The addition of UTAC/Singapore/Thailand is to expand capacity, improve cycle time and to ensure supply continuity. A qualification report is attached (reference: R43297FQ\_USG-UTL\_FCQFN)  
 There are no regulatory compliance changes to the material content of these devices.  
 There are no changes to form/fit/function at new assembler for these devices.

**Impact of the change (positive or negative) on fit, form, function & reliability:**

**Product Identification (this section will describe how to identify the changed material):**

**Summary of Supporting Information:**

**Supporting Documents:**

**ADI Contact Information:**

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

**Appendix A - Impacted items, see csv PN listing in PCN Zip file**